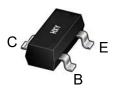


### Features

- Collector Current: I<sub>C</sub>=0.5A
- Power Dissipation of 300mw

## Package Marking and Ordering Information

Product ID	Pack	Qty(PCS)
BC817-16/25/40	SOT-23	3000



**SOT-23** 



# Maxmim Ratings (Ta=25 unless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V <sub>CBO</sub>	50	v
Collector-Emitter Voltage	V <sub>CEO</sub>	45	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Collector Current	I <sub>c</sub>	500	mA
Collector Power Dissipation	Pc	300	mW
Thermal Resistance From Junction To Ambient	R <sub>oja</sub>	417	°C/W
Junction Temperature	Tj	150	°C
Storage Temperature	T <sub>stg</sub>	-55~+150	°C

## **Classifiction Of hFE**

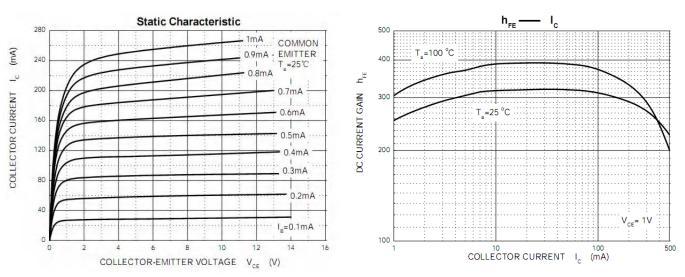
Rank	BC817-16	BC817-25	BC817-40
Range	100-250	160-400	250-600
Marking	6A	6B	6C



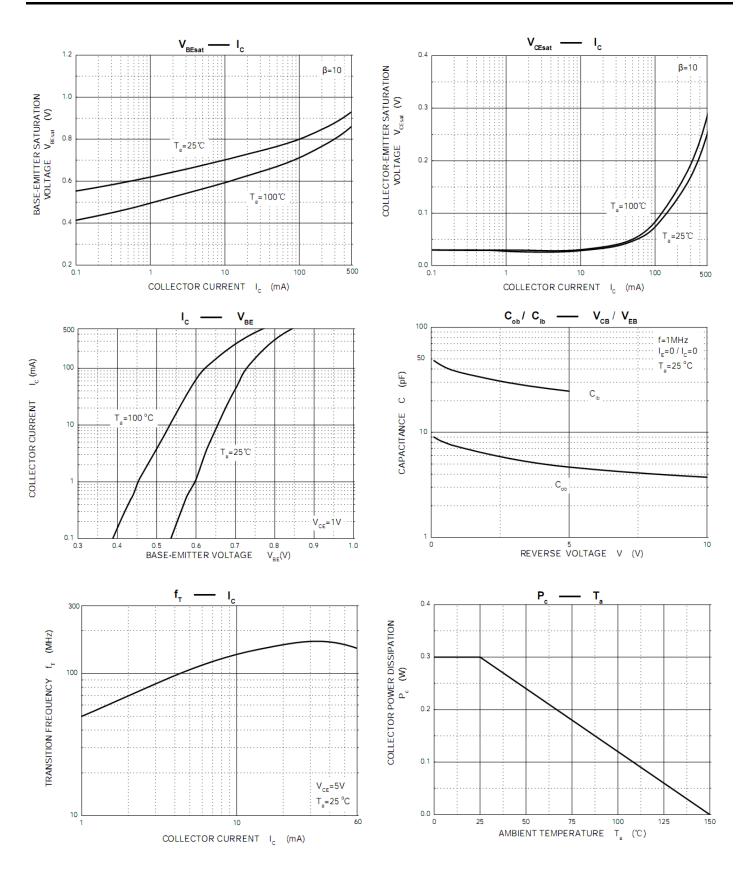
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V <sub>CBO</sub>	b= 10μΑ, I <sub>E</sub> =0	50			V
Collector-emitter breakdown voltage	V <sub>CEO</sub>	I <sub>C</sub> = 10mA, I <sub>B</sub> =0	45			V
Emitter-base breakdown voltage	V <sub>EBO</sub>	Ι <sub>Ε</sub> = 1μΑ, Ι <sub>C</sub> =0	5			V
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 45 V , I <sub>E</sub> =0			0.1	μA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 4V, I <sub>C</sub> =0			0.1	μA
DC current gain	h <sub>FE(1)</sub>	V <sub>CE</sub> = 1V, I <sub>C</sub> = 100mA	100		600	
	h <sub>FE(2)</sub>	V <sub>CE</sub> = 1V, I <sub>C</sub> = 500mA	40			
Collector-emitter saturation voltage	V <sub>CE</sub> (sat)	I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA			0.7	V
Base-emitter saturation voltage	V <sub>BE</sub> (sat)	I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA			1.2	V
Base-emitter voltage	V <sub>BE</sub>	V <sub>CE</sub> = 1 V, I <sub>C</sub> = 500mA			1.2	V
Collecter capactiance	C <sub>ob</sub>	V <sub>CB</sub> =10V ,f=1MHz		10		pF
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 10mA f=100MHz	100			MHz

### Electrcal Charcteristics (Ta=25 unless otherwise specified)

### **Typical Characteristics**

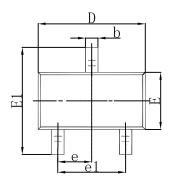


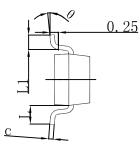


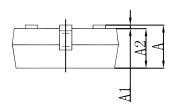




## **SOT-23 Package Outline Dimensions**

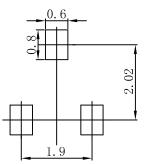






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

## SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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